

## Quik-Pak Supports Advances in Semiconductor Packaging at IMAPS Events

### **IC Packaging Solutions Provider/IMAPS Premier Corporate Member Sponsors Technical Presentation in San Diego Aug. 23, Exhibits at IMAPS Technology Workshop in New York Sept. 22, 2016**

San Diego, CA –PR Newswire - August 23, 2016 – [Quik-Pak](#), a provider of innovative microelectronic packaging and assembly for complex RF/microwave devices, and a Premier Corporate Member of the International Microelectronics Assembly and Packaging Society (IMAPS), will participate in two upcoming IMAPS events:

- On August 23, Quik-Pak will sponsor the IMAPS San Diego Chapter’s luncheon meeting featuring a technical presentation on “*Ambient Temperature Bonding and Liquid Lens Technology for the Internet of Things*” by Invenios EVP & COO Berkeley Johnson.
- On September 22, Quik-Pak will exhibit at IMAPS’ Advanced Technology Workshop examining “*Advances in Semiconductor Packaging*” at the SUNY Polytechnic Institute in Marcy, New York. Experts from around the world will meet to discuss challenges in assembly processes, materials, reliability and packaging, along with recent technological developments that could provide solutions.

Quik-Pak is at the forefront of new packaging technologies, including the development of proprietary [air cavity plastic QFN packages](#), over-molded plastic QFN/DFN packages and custom transfer molded packaging. [Custom IC assembly for ceramic, laminate, COF and COB](#), from prototype design validation to full production, as well as wafer preparation services including dicing, backgrinding and pick and place, are also available. Quik-Pak’s ability to provide a full suite of IC packaging options that are available in three days or less is particularly popular with device manufacturers.

Quik-Pak is a division of [Promex](#), a Silicon Valley-based company featuring [advanced engineering services](#), [mixed SMT assembly and high-reliability IC packaging](#) for medical, biotech, military and commercial device manufacturers. Promex’s 30,000-square-foot assembly facility features Class 100 and 1000 clean rooms for Class III implantable and other complex medical devices. Together, the Quik-Pak and Promex facilities are ISO 13485:2003 and ISO 9001:2008 certified, ITAR registered and compliant to regulatory requirements for medical products.



*Quik-Pak Director of Sales and Marketing Casey Krawiec welcomes attendees to an IMAPS Technical Presentation held at Quik-Pak’s San Diego facility today. Quik-Pak, a provider of innovative microelectronic packaging and assembly for complex RF/microwave devices, will also be exhibiting at IMAPS’ Technology Workshop in Marcy, NY on September 22, 2016. The company specializes in [air cavity plastic QFN packages](#), over-molded plastic QFN/DFN packages and custom transfer molded packaging. [Custom IC assembly for ceramic, laminate, COF and COB](#), from prototype design validation to full production, and wafer preparation services are available. Quik-Pak offers three-days-or-faster turn on IC packaging. [www.icproto.com](http://www.icproto.com)*